DISCRETE SEMICONDUCTORS



Objective specification File under Discrete Semiconductors, SC01 1996 May 24



#### FEATURES

- Glass passivated
- High maximum operating temperature
- Low leakage current
- Excellent stability
- Guaranteed avalanche energy absorption capability
- UL 94V-O classified plastic package
- Shipped in 12 mm embossed tape.

#### DESCRIPTION

DO-214AC surface mountable package with glass passivated chip.

The well-defined void-free case is of a transfer-moulded thermo-setting plastic.



#### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

| SYMBOL             | PARAMETER                                       | CONDITIONS   | MIN. | MAX. | UNIT |
|--------------------|---|--|------|------|------|
| V <sub>RRM</sub>   | repetitive peak reverse voltage                 |  |      |      |      |
|                    | BYG80D  |  | _    | 200  | V    |
|                    | BYG80G  |  | _    | 400  | V    |
|                    | BYG80J  |  | _    | 600  | V    |
| V <sub>R</sub>     | continuous reverse voltage                      |  |      |      |      |
|                    | BYG80D  |  | _    | 200  | V    |
|                    | BYG80G  |  | _    | 400  | V    |
|                    | BYG80J  |  | _    | 600  | V    |
| I <sub>F(AV)</sub> | average forward current                         | averaged over any 20 ms period;<br>$T_{tp}$ = 135 °C                         |      |      |      |
|                    | BYG80D  |  | _    | 1.6  | A    |
|                    | BYG80G  |  | _    | 1.5  | A    |
|                    | BYG80J  |  | _    | 1.1  | A    |
| I <sub>FSM</sub>   | non-repetitive peak forward current             | t = 10 ms half sine wave;  |      |      |      |
|                    | BYG80D  | $T_j = T_{j max}$ prior to surge;  | _    | 36   | A    |
|                    | BYG80G  | $V_{R} = V_{RRMmax}$   | _    | 32   | A    |
|                    | BYG80J  |  | _    | 32   | A    |
| E <sub>RSM</sub>   | non-repetitive peak reverse<br>avalanche energy | L = 120 mH; $T_j = T_{j max}$ prior to surge;<br>inductive load switched off | _    | 10   | mJ   |
| T <sub>stg</sub>   | storage temperature                             |  | -65  | +175 | °C   |
| Tj                 | junction temperature                            |  | -65  | +175 | °C   |

## **BYG80** series

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#### **ELECTRICAL CHARACTERISTICS**

 $T_i = 25 \ ^{\circ}C$  unless otherwise specified.

| SYMBOL          | PARAMETER             | CONDITIONS  | MAX. | UNIT |
|-----------------|-----------------------|---|------|------|
| V <sub>F</sub>  | forward voltage       | I <sub>F</sub> = 1 A; T <sub>j</sub> = 150 °C     |      |      |
|                 | BYG80D                |   | 0.71 | V    |
|                 | BYG80G                |   | 0.77 | V    |
|                 | BYG80J                |   | 1.05 | V    |
| V <sub>F</sub>  | forward voltage       | I <sub>F</sub> = 1 A                              |      |      |
|                 | BYG80D                |   | 0.93 | V    |
|                 | BYG80G                |   | 0.98 | V    |
|                 | BYG80J                |   | 1.25 | V    |
| I <sub>R</sub>  | reverse current       | V <sub>R</sub> = V <sub>RRMmax</sub>              | 1    | μA   |
|                 | BYG80D                | $V_R = V_{RRMmax}; T_j = 165 \ ^\circ C$          | 100  | μA   |
|                 | BYG80G                |   | 150  | μA   |
|                 | BYG80J                |   | 150  | μA   |
| t <sub>rr</sub> | reverse recovery time | when switched from $I_F = 0.5 A$ to $I_R = 1 A$ ; |      |      |
|                 | BYG80D                | measured at $I_R = 0.25$ A; see Fig.2             | 25   | ns   |
|                 | BYG80G                |   | 50   | ns   |
|                 | BYG80J                |   | 50   | ns   |

#### THERMAL CHARACTERISTICS

| SYMBOL               | PARAMETER                                     | CONDITIONS | VALUE | UNIT |
|----------------------|---|------------|-------|------|
| R <sub>th j-tp</sub> | thermal resistance from junction to tie-point |            | 25    | K/W  |
| R <sub>th j-a</sub>  | thermal resistance from junction to ambient   | note 1     | 100   | K/W  |
|                      |   | note 2     | 150   | K/W  |

#### Notes

1. Device mounted on Al<sub>2</sub>O<sub>3</sub> printed-circuit board, 0.7 mm thick; thickness of copper  $\ge$ 35 µm, see Fig.3.

2. Device mounted on epoxy-glass printed-circuit board, 1.5 mm thick; thickness of copper ≥40 μm, see Fig.3. For more information please refer to the *'General Part of Handbook SC01'*.

## BYG80 series

#### **GRAPHICAL DATA**





#### PACKAGE OUTLINE



#### DEFINITIONS

| Data sheet status   |   |  |  |
|---|---|--|--|
| Objective specification   | This data sheet contains target or goal specifications for product development.       |  |  |
| Preliminary specification   | This data sheet contains preliminary data; supplementary data may be published later. |  |  |
| Product specification   | This data sheet contains final product specifications.                                |  |  |
| Limiting values   |   |  |  |
| Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability. |   |  |  |
| Application information   |   |  |  |
| Where application information is given, it is advisory and does not form part of the specification.   |   |  |  |

#### LIFE SUPPORT APPLICATIONS

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